Infineon Technologies - MB90387SPMT-GS-144 Datasheet

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	16MHz
Connectivity	CANbus, SCI, UART/USART
Peripherals	POR, WDT
Number of I/O	36
Program Memory Size	64KB (64K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90387spmt-gs-144

DTP/External Interrupt: 4 channels, CAN wakeup: 1channel

- Module for activation of expanded intelligent I/O service (EI^2OS), and generation of external interrupt.

Delay Interrupt Generator Module

- Generates interrupt request for task switching.

8/10-bit A/D Converter: 8 channels

- Resolution is selectable between 8-bit and 10-bit.
- Activation by external trigger input is allowed.
- Conversion time: 6.125 μs (at 16 MHz machine clock, including sampling time)

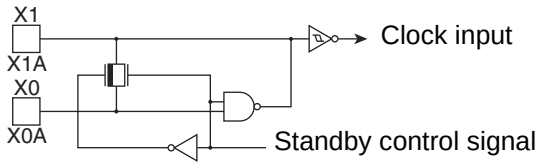
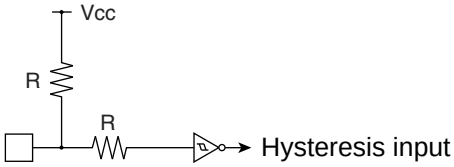
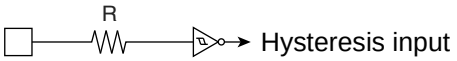
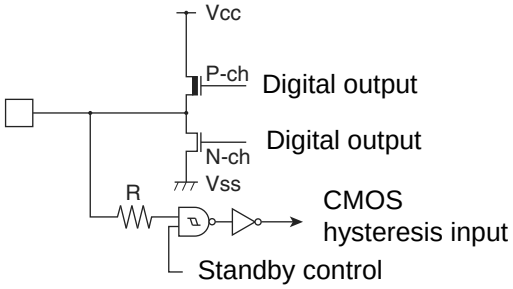
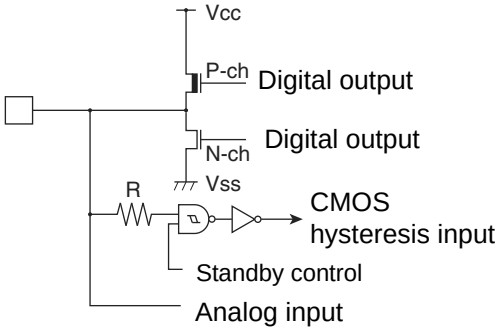
Program Patch Function

- Address matching detection for 2 address pointers.

1. Product Lineup

Parameter \ Part Number		MB90F387 MB90F387S	MB90387 MB90387S	MB90V495G
Classification		Flash ROM	Mask ROM	Evaluation product
ROM capacity		64 Kbytes		–
RAM capacity		2 Kbytes		6 Kbytes
Process		CMOS		
Package		LQFP-48 (pin pitch 0.50 mm)		PGA-256
Operating power supply voltage		3.5 V to 5.5 V		4.5 V to 5.5 V
Special power supply for emulator*1		–		None
CPU functions		Number of basic instructions : 351 instructions Instruction bit length : 8 bits and 16 bits Instruction length : 1 byte to 7 bytes Data bit length : 1 bit, 8 bits, 16 bits		
		Minimum instruction execution time: 62.5 ns (at 16 MHz machine clock)		
		Interrupt processing time: 1.5 μs at minimum (at 16 MHz machine clock)		
Low power consumption (standby) mode		Sleep mode / Watch mode / Time-base timer mode / Stop mode / CPU intermittent		
I/O port		General-purpose input/output ports (CMOS output): 34 ports (36 ports*2) including 4 high-current output ports (P14 to P17)		
Time-base timer		18-bit free-run counter Interrupt cycle: 1.024 ms, 4.096 ms, 16.834 ms, 131.072 ms (with oscillation clock frequency at 4 MHz)		
Watchdog timer		Reset generation cycle: 3.58 ms, 14.33 ms, 57.23 ms, 458.75 ms (with oscillation clock frequency at 4 MHz)		
16-bit input/ output timer	16-bit free-run timer	Number of channels: 1 Interrupt upon occurrence of overflow		
	Input capture	Number of channels: 4 Retaining free-run timer value set by pin input (rising edge, falling edge, and both edges)		
16-bit reload timer		Number of channels: 2 16-bit reload timer operation Count clock cycle: 0.25 μs, 0.5 μs, 2.0 μs (at 16-MHz machine clock frequency) External event count is allowed.		
Watch timer		15-bit free-run counter Interrupt cycle: 31.25 ms, 62.5 ms, 12 ms, 250 ms, 500 ms, 1.0 s, 2.0 s (with 8.192 kHz sub clock)		
8/16-bit PPG timer		Number of channels: 2 (four 8-bit channels are available also.) PPG operation is allowed with four 8-bit channels or two 16-bit channels. Outputting pulse wave of arbitrary cycle or arbitrary duty is allowed. Count clock: 62.5 ns to 1 μs (with 16 MHz machine clock)		
Delay interrupt generator module		Interrupt generator module for task switching. Used for realtime OS.		
DTP/External interrupt		Number of inputs: 4 Activated by rising edge, falling edge, “H” level or “L” level input. External interrupt or expanded intelligent I/O service (EI^{2}OS) is available.		

6. I/O Circuit Type

Type	Circuit	Remarks
A		■ High-rate oscillation feedback resistor, approx.1 MΩ ■ Low-rate oscillation feedback resistor, approx.10 MΩ
B		■ Hysteresis input with pull-up resistor. ■ Pull-up resistor, approx.50 kΩ
C		■ Hysteresis input
D		■ CMOS hysteresis input ■ CMOS level output ■ Standby control provided
E		■ CMOS hysteresis input ■ CMOS level output ■ Shared for analog input pin ■ Standby control provided

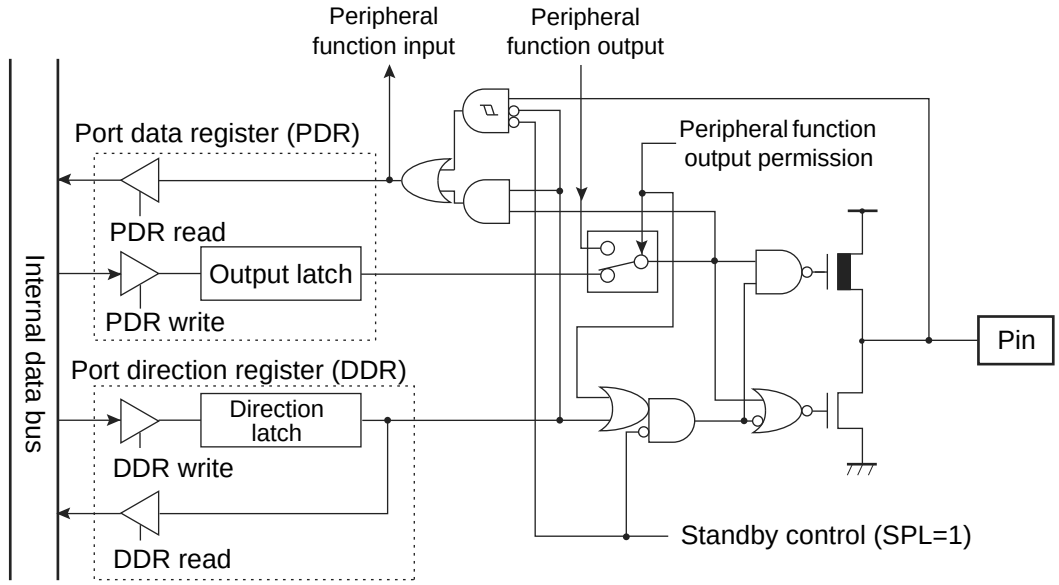
Address	Register Abbreviation	Register	Read/ Write	Resource	Initial Value
003910H	PRLL0	PPG0 reload register L	R/W	8/16-bit PPG timer	XXXXXXXXB
003911H	PRLH0	PPG0 reload register H	R/W		XXXXXXXXB
003912H	PRLL1	PPG1 reload register L	R/W		XXXXXXXXB
003913H	PRLH1	PPG1 reload register H	R/W		XXXXXXXXB
003914H	PRLL2	PPG2 reload register L	R/W		XXXXXXXXB
003915H	PRLH2	PPG2 reload register H	R/W		XXXXXXXXB
003916H	PRLL3	PPG3 reload register L	R/W		XXXXXXXXB
003917H	PRLH3	PPG3 reload register H	R/W		XXXXXXXXB
003918H to 00392FH	(Reserved area) *				
003930H to 003BFFH	(Reserved area) *				
003C00H to 003C0FH	RAM (General-purpose RAM)				
003C10H to 003C13H	IDR0	ID register 0	R/W	CAN controller	XXXXXXXXB to XXXXXXXXB
003C14H to 003C17H	IDR1	ID register 1	R/W		XXXXXXXXB to XXXXXXXXB
003C18H to 003C1BH	IDR2	ID register 2	R/W		XXXXXXXXB to XXXXXXXXB
003C1CH to 003C1FH	IDR3	ID register 3	R/W		XXXXXXXXB to XXXXXXXXB
003C20H to 003C23H	IDR4	ID register 4	R/W		XXXXXXXXB to XXXXXXXXB
003C24H to 003C27H	IDR5	ID register 5	R/W		XXXXXXXXB to XXXXXXXXB
003C28H to 003C2BH	IDR6	ID register 6	R/W		XXXXXXXXB to XXXXXXXXB
003C2CH to 003C2FH	IDR7	ID register 7	R/W		XXXXXXXXB to XXXXXXXXB
003C30H, 003C31H	DLCR0	DLC register 0	R/W		XXXXXXXXB, XXXXXXXXB
003C32H, 003C33H	DLCR1	DLC register 1	R/W		XXXXXXXXB, XXXXXXXXB
003C34H, 003C35H	DLCR2	DLC register 2	R/W		XXXXXXXXB, XXXXXXXXB
003C36H, 003C37H	DLCR3	DLC register 3	R/W		XXXXXXXXB, XXXXXXXXB

Address	Register Abbreviation	Register	Read/ Write	Resource	Initial Value
003C38H, 003C39H	DLCR4	DLC register 4	R/W	CAN controller	XXXXXXXXB, XXXXXXXXB
003C3AH, 003C3BH	DLCR5	DLC register 5	R/W		XXXXXXXXB, XXXXXXXXB
003C3CH, 003C3DH	DLCR6	DLC register 6	R/W		XXXXXXXXB, XXXXXXXXB
003C3EH, 003C3FH	DLCR7	DLC register 7	R/W		XXXXXXXXB, XXXXXXXXB
003C40H to 003C47H	DTR0	Data register 0	R/W		XXXXXXXXB to XXXXXXXXB
003C48H to 003C4FH	DTR1	Data register 1	R/W		XXXXXXXXB to XXXXXXXXB
003C50H to 003C57H	DTR2	Data register 2	R/W		XXXXXXXXB to XXXXXXXXB
003C58H to 003C5FH	DTR3	Data register 3	R/W		XXXXXXXXB to XXXXXXXXB
003C60H to 003C67H	DTR4	Data register 4	R/W		XXXXXXXXB to XXXXXXXXB
003C68H to 003C6FH	DTR5	Data register 5	R/W		XXXXXXXXB to XXXXXXXXB
003C70H to 003C77H	DTR6	Data register 6	R/W		XXXXXXXXB to XXXXXXXXB
003C78H to 003C7FH	DTR7	Data register 7	R/W		XXXXXXXXB to XXXXXXXXB
003C80H to 003CFFH	(Reserved area) *				
003D00H, 003D01H	CSR	Control status register	R/W, R	CAN controller	0XXXX001B, 00XXX000B
003D02H	LEIR	Last event display register	R/W		000XX000B
003D03H	(Reserved area) *				
003D04H, 003D05H	RTEC	Send/receive error counter	R	CAN controller	00000000B, 00000000B
003D06H, 003D07H	BTR	Bit timing register	R/W		11111111B, X1111111B
003D08H	IDER	IDE register	R/W		XXXXXXXXB
003D09H	(Reserved area) *				
003D0AH	TRTRR	Send RTR register	R/W	CAN controller	00000000B
003D0BH	(Reserved area) *				
003D0CH	RFWTR	Remote frame receive wait register	R/W	CAN controller	XXXXXXXXB

11. Interrupt Sources, Interrupt Vectors, And Interrupt Control Registers

Interrupt Source	EI²OS Readiness	Interrupt Vector			Interrupt Control Register		Priority*3
		Number		Address	ICR	Address	
Reset	×	#08	08H	FFFFDCH	–	–	High
INT 9 instruction	×	#09	09H	FFFFD8H	–	–	↑
Exceptional treatment	×	#10	0AH	FFFFD4H	–	–	
CAN controller reception completed (RX)	´	#11	0BH	FFFFD0H	ICR00	0000B0H*1	
CAN controller transmission completed (TX) / Node status transition (NS)	´	#12	0CH	FFFFCCH			
Reserved	×	#13	0DH	FFFFC8H	ICR01	0000B1H	
Reserved	×	#14	0EH	FFFFC4H			
CAN wakeup	Δ	#15	0FH	FFFFC0H	ICR02	0000B2H*1	
Time-base timer	×	#16	10H	FFFFBCH			
16-bit reload timer 0	Δ	#17	11H	FFFFB8H	ICR03	0000B3H*1	
8/10-bit A/D converter	Δ	#18	12H	FFFFB4H			
16-bit free-run timer overflow	Δ	#19	13H	FFFFB0H	ICR04	0000B4H*1	
Reserved	×	#20	14H	FFFFACH			
Reserved	×	#21	15H	FFFFA8H	ICR05	0000B5H*1	
PPG timer ch0, ch1 underflow	´	#22	16H	FFFFA4H			
Input capture 0-input	Δ	#23	17H	FFFFA0H	ICR06	0000B6H*1	
External interrupt (INT4/INT5)	Δ	#24	18H	FFFF9CH			
Input capture 1-input	Δ	#25	19H	FFFF98H	ICR07	0000B7H*2	
PPG timer ch2, ch3 underflow	´	#26	1AH	FFFF94H			
External interrupt (INT6/INT7)	Δ	#27	1BH	FFFF90H	ICR08	0000B8H*1	
Watch timer	Δ	#28	1CH	FFFF8CH			
Reserved	×	#29	1DH	FFFF88H	ICR09	0000B9H*1	
Input capture 2-input Input capture 3-input	´	#30	1EH	FFFF84H			
Reserved	×	#31	1FH	FFFF80H	ICR10	0000BAH*1	
Reserved	×	#32	20H	FFFF7CH			
Reserved	×	#33	21H	FFFF78H	ICR11	0000BBH*1	
Reserved	×	#34	22H	FFFF74H			
Reserved	×	#35	23H	FFFF70H	ICR12	0000BCH*1	↓
16-bit reload timer 1	○	#36	24H	FFFF6CH			Low

Port 1 Pins Block Diagram (single-chip mode)



Standby control: Control among Stop mode (SPL=1), Time-base timer mode (SPL=1), and watch mode (SPL=1).

Port 1 Registers (single-chip mode)

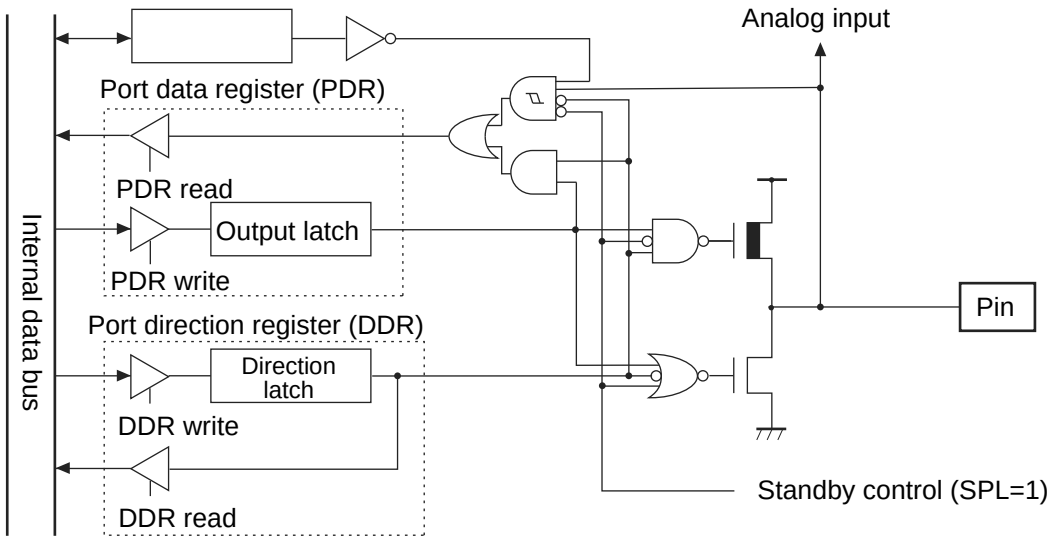
■ Port 1 registers include port 1 data register (PDR1) and port 1 direction register (DDR1).

■ The bits configuring the register correspond to port 1 pins on a one-to-one basis.

Relation between Port 1 Registers and Pins

Port Name	Bits of Register and Corresponding Pins								
Port 1	PDR1, DDR1	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
	Corresponding pins	P17	P16	P15	P14	P13	P12	P11	P10

Port 5 Pins Block Diagram



Standby control: Control among Stop mode (SPL=1), Time-base timer mode (SPL=1), and watch mode (SPL=1).

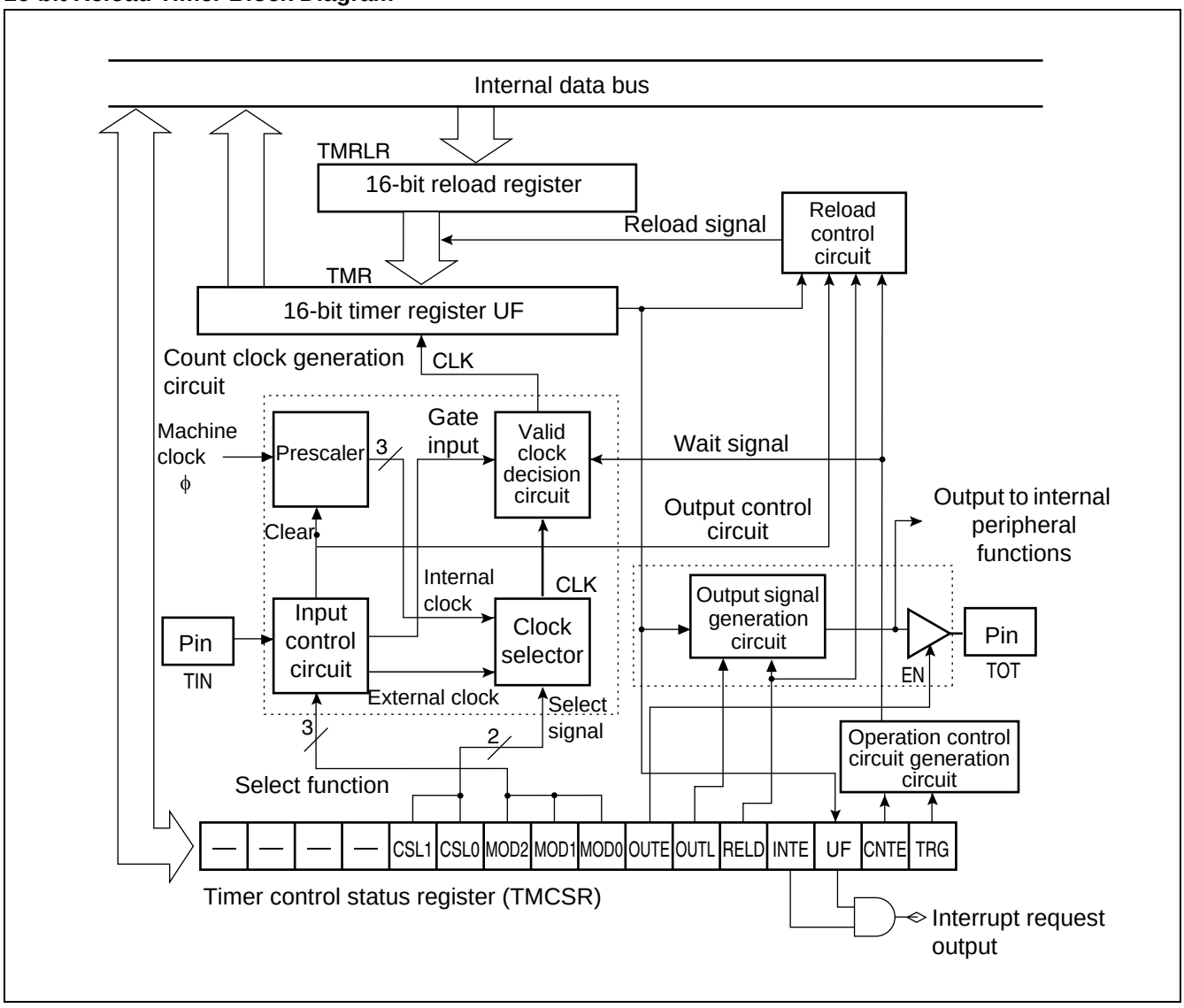
Port 5 Registers

- Port 5 registers include port 5 data register (PDR5), port 5 direction register (DDR5), and analog input permission register (ADER).
- Analog input permission register (ADER) allows or disallows input of analog signal to the analog input pin.
- The bits configuring the register correspond to port 5 pins on a one-to-one basis.

Relation between Port 5 Registers and Pins

Port Name	Bits of Register and Corresponding Pins								
Port 5	PDR5, DDR5	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
	ADER	ADE7	ADE6	ADE5	ADE4	ADE3	ADE2	ADE1	ADE0
	Corresponding pins	P57	P56	P55	P54	P53	P52	P51	P50

16-bit Reload Timer Block Diagram



12.7 8/16-bit PPG Timer Outline

The 8/16-bit PPG timer is a 2-channel reload timer module (PPG0 and PPG1) that allows outputting pulses of arbitrary cycle and duty cycle. Combination of the two channels allows selection among the following operations:

- 8-bit PPG output 2-channel independent operation mode
- 16-bit PPG output operation mode
- 8-bit and 8-bit PPG output operation mode

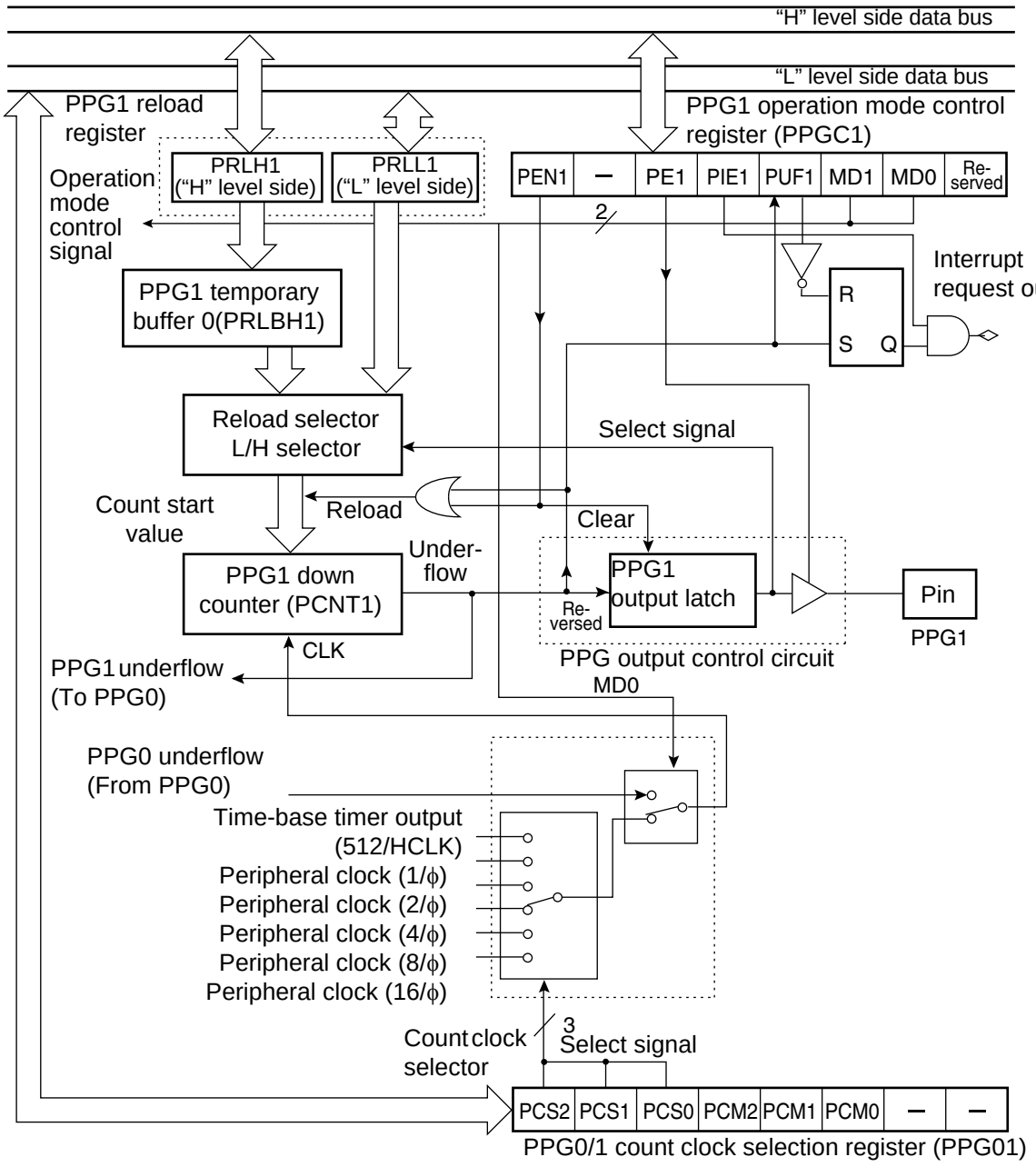
MB90385 series device has two 8/16-bit built-in PPG timers. This section describes functions of PPG0/1. PPG2/3 have the same functions as those of PPG0/1.

Functions of 8/16-bit PPG Timer

The 8/16-bit PPG timer is composed of four 8-bit reload register (PRLH0/PRLL0, PRLH1/PRLL1) and two PPG down counters (PCNT0, PCNT1).

- Widths of “H” and “L” in output pulse are specifiable independently. Cycle and duty factor of output pulse is specifiable arbitrarily.
- Count clock is selectable among 6 internal clocks.
- The timer is usable as an interval timer, by generating interrupt requests for each interval.
- The time is usable as a D/A converter, with an external circuit.

8/16-bit PPG Timer 1 Block Diagram



– : Undefined
Reserved: Reserved bit
HCLK : Oscillation clock frequency
ϕ : Machine clock frequency
* : Interrupt output of 8/16-bit PPG timer 1 is incorporated into one by the OR circuit against interrupt output of 8/16-bit PPG timer 0.

12.12 CAN Controller

The Controller Area Network (CAN) is a serial communication protocol compliant with CANVer2.0A and Ver2.0B. The protocol allows data transmission and reception in both standard frame format and expanded frame format.

Features of CAN Controller

- CAN controller format is compliant with CANVer2.0A and Ver2.0B.
- The protocol allows data transmission and reception in standard frame format and expanded frame format.
- Automatic transmission of data frame by remote frame reception is allowed.
- Baud rate ranges from 10 kbps to 1 Mbps (with 16-MHz machine clock).

Table 12-5. Data Transmission Baud Rate

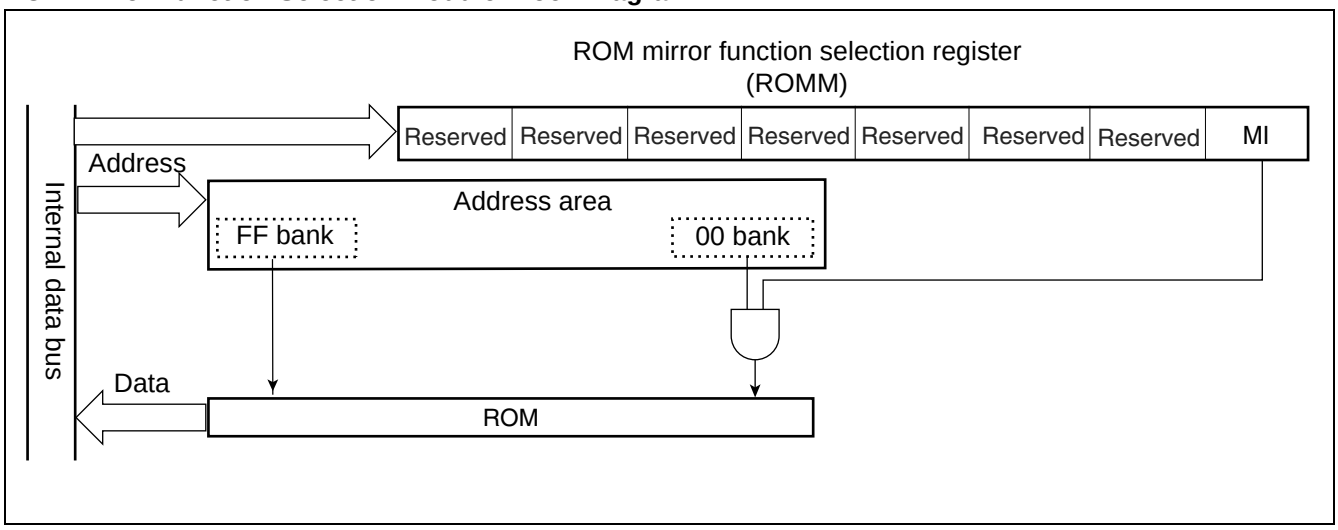
Machine Clock	Baud Rate (Max)
16 MHz	1 Mbps
12 MHz	1 Mbps
8 MHz	1 Mbps
4 MHz	500 kbps
2 MHz	250 kbps

- Provided with 8 transmission/reception message buffers.
- Transmission/reception is allowed at ID 11 bit in standard format, and at ID 29 bit in expanded frame format.
- Specifying 0 byte to 8 bytes is allowed in message data.
- Multi-level message buffer configuration is allowed.
- CAN controller has two built-in acceptance masks. Mask settings are independently allowed for the two acceptance masks on reception IDs.
- The two acceptance masks allow reception in standard frame format and expanded frame format.
- For types of masking, all-bit comparison, all-bit masking, and partial masking with acceptance mask register 0/1, are specifiable.

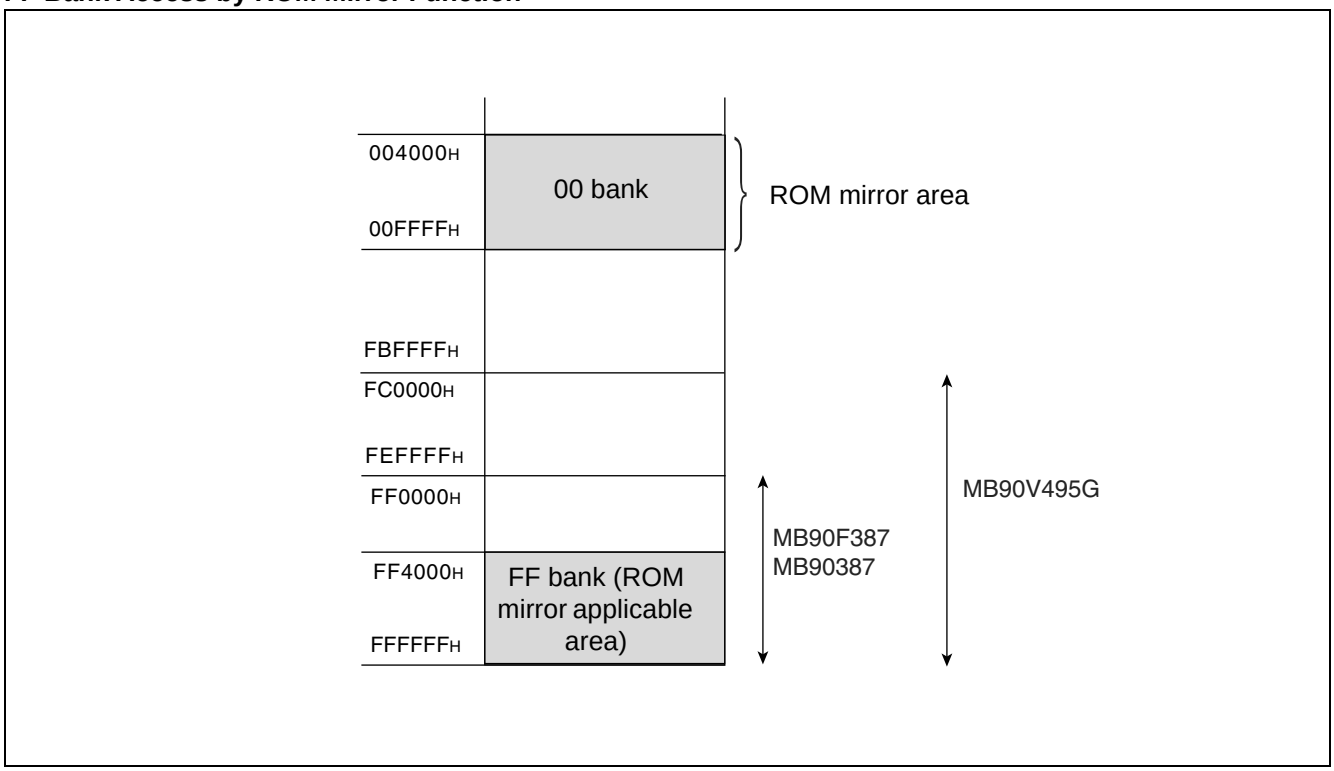
12.14 ROM Mirror Function Selection Module Outline

The ROM mirror function selection module sets the data in ROM assigned to FF bank so that the data is read by access to 00 bank.

ROM Mirror Function Selection Module Block Diagram



FF Bank Access by ROM Mirror Function



12.15 512 Kbit Flash Memory Outline

The following three methods are provided for data writing and deleting on Flash memory:

1. Parallel writer
2. Serial special-purpose writer
3. Writing/deleting by program execution

This section describes “3. Writing/deleting by program execution.”

512 Kbit Flash Memory Outline

The 512 Kbit Flash memory is allocated on FF_H bank of CPU memory map. Using the function of Flash memory interface circuit, the memory allows read access and program access from CPU.

Writing/deleting on Flash memory is performed by instruction from CPU via Flash memory interface. Because rewriting is allowed on mounted memory, modifying program and data is performed efficiently.

Features of 512 Kbit Flash Memory

- 128 K words x 8 bits/64 K words x 16 bits (16 K + 8 K + 8 K + 32 K) sector configuration
- Automatic program algorithm (Embedded Algorithm: Similar to MBM29LV200.)
- Built-in deletion pause/deletion resume function
- Detection of completed writing/deleting by data polling and toggle bits.
- Detection of completed writing/deleting by CPU interrupt.
- Deletion is allowed on a sector-by-sector basis (sectors are combined freely).
- Number of writing/deleting operations (minimum): 10,000 times
- Sector protection
- Expanded sector protection
- Temporaly sector unprotection

Note: A function of reading manufacture code and device code is not provided. These codes are not accessible by command either.

Flash Memory Writing/Deleting

- Writing and reading data is not allowed simultaneously on the Flash memory.
- Data writing and deleting on the Flash memory is performed by the processes as follows: Make a copy of program on Flash memory onto RAM. Then, execute the program copied on the RAM.

List of Registers and Reset Values in Flash Memory

Flash memory control status register (FMCS)

bit	7	6	5	4	3	2	1	0
	0	0	0	X	0	0	0	0

× : Undefined

Sector Configuration

For access from CPU, SA0 to SA3 are allocated in FF bank register.

13. Electrical Characteristics

13.1 Absolute Maximum Rating

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1	V_{CC}	V_{SS} – 0.3	V_{SS} + 6.0	V	
	AV_{CC}	V_{SS} – 0.3	V_{SS} + 6.0	V	$V_{CC} = AV_{CC}$*2
	AVR	V_{SS} – 0.3	V_{SS} + 6.0	V	$AV_{CC} \geq AVR$*2
Input voltage*1	V_I	V_{SS} – 0.3	V_{SS} + 6.0	V	*3
Output voltage*1	V_O	V_{SS} – 0.3	V_{SS} + 6.0	V	*3
Maximum clamp current	I_{CLAMP}	– 2.0	+ 2.0	mA	*7
Total maximum clamp current	$\Sigma \mid I_{CLAMP} \mid$	–	20	mA	*7
“L” level maximum output current	I_{OL1}	–	15	mA	Normal output*4
	I_{OL2}	–	40	mA	High-current output*4
“L” level average output current	I_{OLAV1}	–	4	mA	Normal output*5
	I_{OLAV2}	–	30	mA	High-current output*5
“L” level maximum total output current	ΣI_{OL1}	–	125	mA	Normal output
	ΣI_{OL2}	–	160	mA	High-current output
“L” level average total output current	ΣI_{OLAV1}	–	40	mA	Normal output*6
	ΣI_{OLAV2}	–	40	mA	High-current output*6
“H” level maximum output current	I_{OH1}	–	–15	mA	Normal output*4
	I_{OH2}	–	–40	mA	High-current output*4
“H” level average output current	I_{OHAV1}	–	–4	mA	Normal output*5
	I_{OHAV2}	–	–30	mA	High-current output*5
“H” level maximum total output current	ΣI_{OH1}	–	–125	mA	Normal output
	ΣI_{OH2}	–	–160	mA	High-current output
“H” level average total output current	ΣI_{OHAV1}	–	–40	mA	Normal output*6
	ΣI_{OHAV2}	–	–40	mA	High-current output*6
Power consumption	P_D	–	245	mW	
Operating temperature	T_A	–40	+105	°C	
Storage temperature	Tstg	–55	+150	°C	

*1: The parameter is based on $V_{SS} = AV_{SS} = 0.0$ V.

*2: AVcc and AVR should not exceed Vcc.

*3: V_I and V_O should not exceed Vcc + 0.3 V. However if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

*4: A peak value of an applicable one pin is specified as a maximum output current.

*5: An average current value of an applicable one pin within 100 ms is specified as an average output current. (Average value is found by multiplying operating current by operating rate.)

*6: An average current value of all pins within 100 ms is specified as an average total output current. (Average value is found by multiplying operating current by operating rate.)

*7:

■ Applicable to pins: P10 to P17, P20 to P27, P30 to P33, P35*, P36*, P37, P40 to P44, P50 to P57
*: P35 and P36 are MB90387S and MB90F387S only.

13.3 DC Characteristics

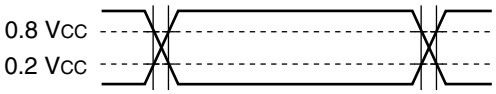
(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
"H" level input voltage	V_{IHS}	CMOS hysteresis input pin	—	0.8 V_{CC}	—	V_{CC} + 0.3	V	
	V_{IHM}	MD input pin	—	V_{CC} – 0.3	—	V_{CC} + 0.3	V	
"L" level input voltage	V_{ILS}	CMOS hysteresis input pin	—	V_{SS} – 0.3	—	0.2 V_{CC}	V	
	V_{ILM}	MD input pin	—	V_{SS} – 0.3	—	V_{SS} + 0.3	V	
"H" level output voltage	V_{OH1}	Pins other than P14 to P17	V_{CC} = 4.5 V, I_{OH} = –4.0 mA	V_{CC} – 0.5	—	—	V	
	V_{OH2}	P14 to P17	V_{CC} = 4.5 V, I_{OH} = –14.0 mA	V_{CC} – 0.5	—	—	V	
"L" level output voltage	V_{OL1}	Pins other than P14 to P17	V_{CC} = 4.5 V, I_{OL} = 4.0 mA	—	—	0.4	V	
	V_{OL2}	P14 to P17	V_{CC} = 4.5 V, I_{OL} = 20.0 mA	—	—	0.4	V	
Input leak current	I_{IL}	All input pins	V_{CC} = 5.5 V, V_{SS} < V_I < V_{CC}	–5	—	+5	µA	
Power supply current*	I_{CC}	V_{CC}	V_{CC} = 5.0 V, Internally operating at 16 MHz, normal operation.	—	25	30	mA	
			V_{CC} = 5.0 V, Internally operating at 16 MHz, writing on Flash memory.	—	45	50	mA	MB90F387/S
			V_{CC} = 5.0 V, Internally operating at 16 MHz, deleting on Flash memory.	—	45	50	mA	MB90F387/S
	I_{CCS}		V_{CC} = 5.0 V, Internally operating at 16 MHz, sleeping.	—	8	12	mA	
	I_{CTS}		V_{CC} = 5.0 V, Internally operating at 2 MHz, transition from main clock mode, in time-base timer mode.	—	0.75	1.0	mA	MB90F387/S
					0.2	0.35		MB90387/S

Rating values of alternating current is defined by the measurement reference voltage values shown below:

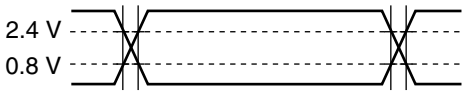
- Input signal waveform

Hysteresis input pin



- Output signal waveform

Output pin



13.4.2 Reset Input Timing

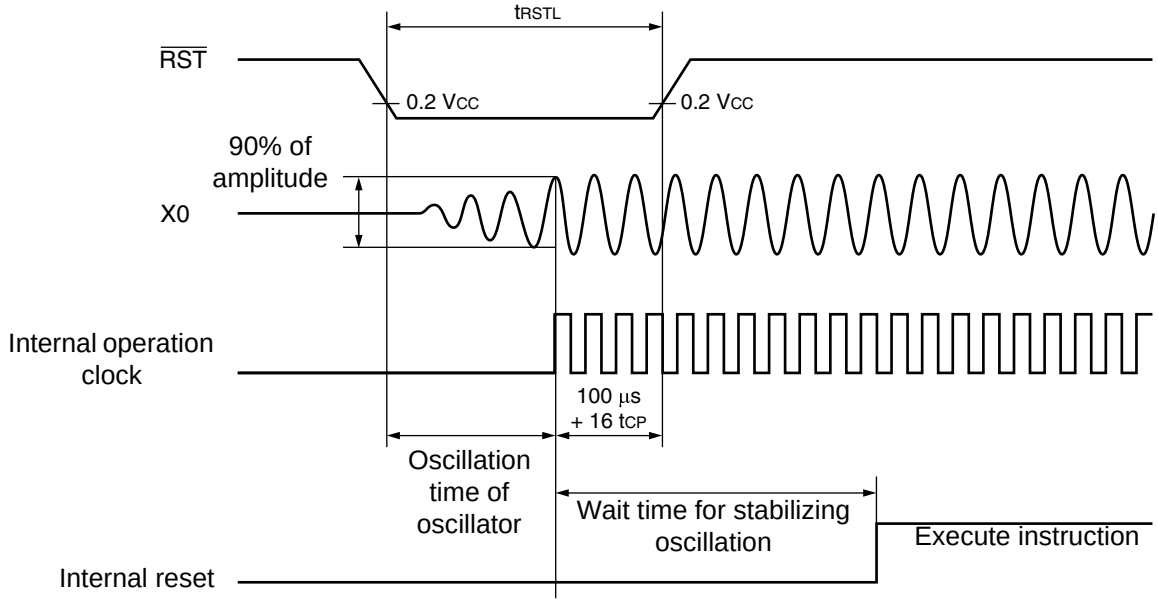
Parameter	Symbol	Pin Name	Value		Unit	Remarks
			Min	Max		
Reset input time	t_{RSTL}	RST	16 t_{CP}*3	–	ns	Normal operation
			Oscillation time of oscillator*1 + 100 μs + 16 t_{CP}*3	–	–	In sub clock*2, sub sleep*2, watch*2 and stop mode
			100	–	μs	In timebase timer

*1: Oscillation time of oscillator is time that the amplitude reached the 90%. In the crystal oscillator, the oscillation time is between several ms to tens of ms. In ceramic oscillator, the oscillation time is between hundreds of μs to several ms. In the external clock, the oscillation time is 0 ms.

*2: Except for MB90F387S and MB90387S.

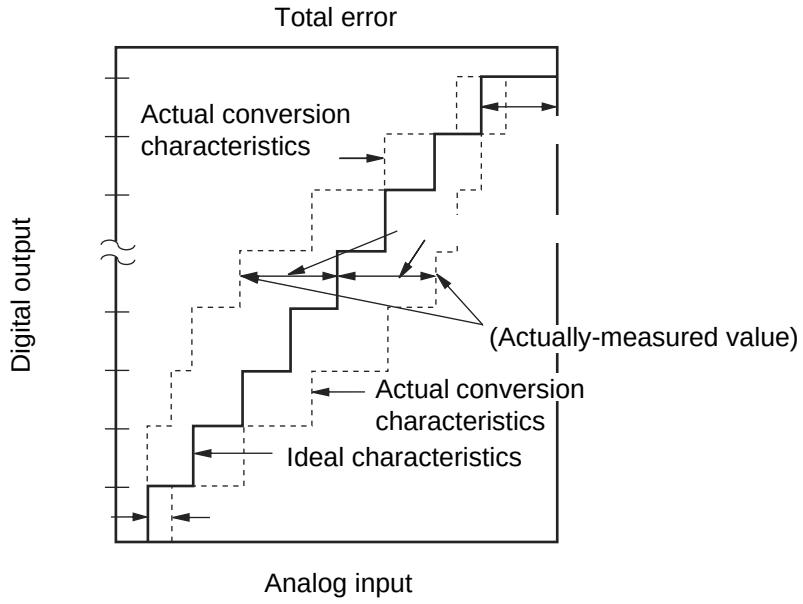
*3: Refer to "(1) Clock timing" ratings for t_{CP} (internal operation clock cycle time).

- In sub clock, sub sleep, watch and stop mode



13.6 Definition of A/D Converter Terms

Resolution:	Analog variation that is recognized by an A/D converter.
Linear error:	Deviation between a line across zero-transition line (“00 0000 00 0 0” ←→“00 0000 0001”) and full-scale transition line (“11 1111 11 1 0” ←→ “11 1111 1111”) and actual conversion characteristics.
Differential linear error:	Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
Total error:	Difference between an actual value and an ideal value. A total error includes zero transition error, full-scale transition error, and linear error.



$$\text{Total error of digital output “N”} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + 0.5\ \text{LSB}\}}{1\ \text{LSB}} \quad [\text{LSB}]$$

$$1\ \text{LSB} = (\text{Ideal value})\ \frac{AVR - AV_{SS}}{1024}\ [V]$$

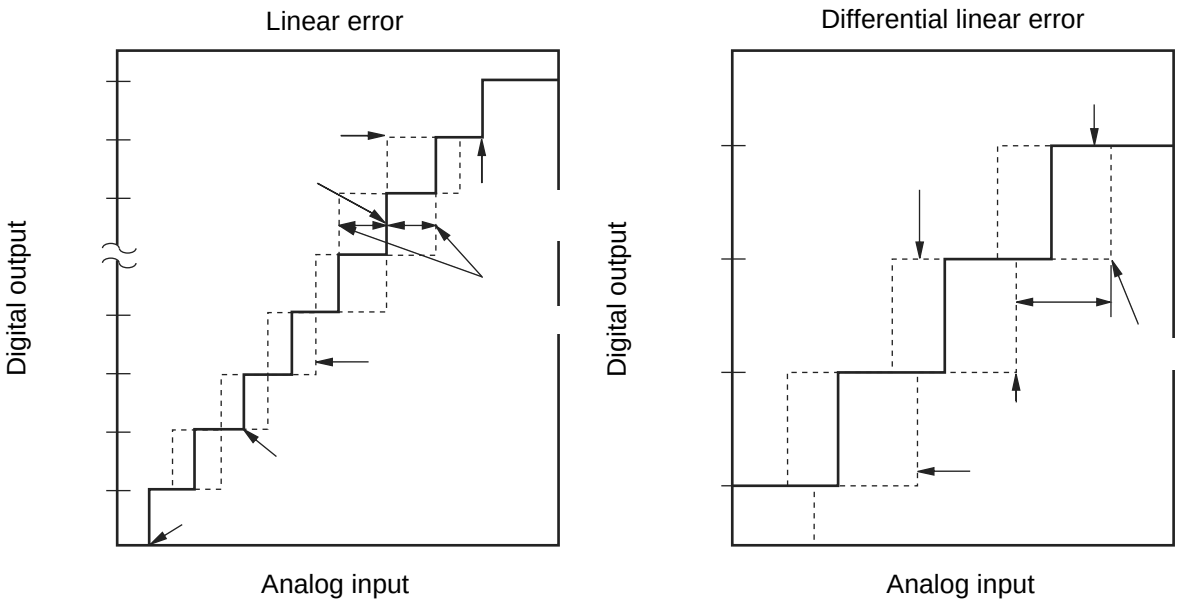
V_{OT} (Ideal value) = AV_{SS} + 0.5 LSB [V]

V_{FST} (Ideal value) = AVR − 1.5 LSB [V]

V_{NT}: A voltage at which digital output transits from $(N\text{-}1)_H$ to N_H.

(Continued)

(Continued)



$$\text{Linear error of digital output N} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + V_{OT}\}}{1\ \text{LSB}}\ [\text{LSB}]$$

$$\text{Differential linear error of digital output N} = \frac{V_{(N+1)T} - V_{NT}}{1\ \text{LSB}} - 1\text{LSB}\ [\text{LSB}]$$

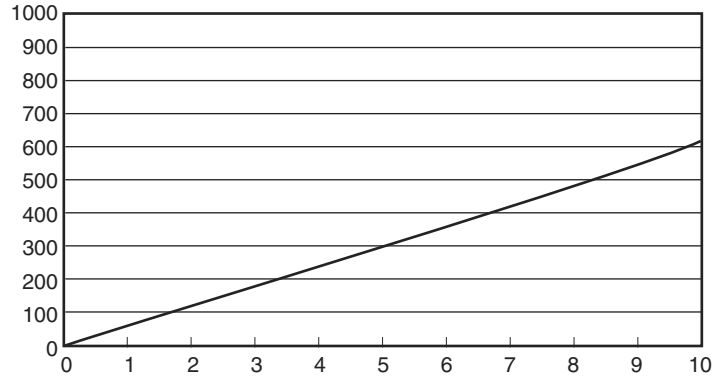
$$1\ \text{LSB} = \frac{V_{FST} - V_{OT}}{1022}\ [\text{V}]$$

V_{OT}: Voltage at which digital output transits from “000_H” to “001_H.”
V_{FST}: Voltage at which digital output transits from “$3FE_H$” to “$3FF_H$.”

(Continued)

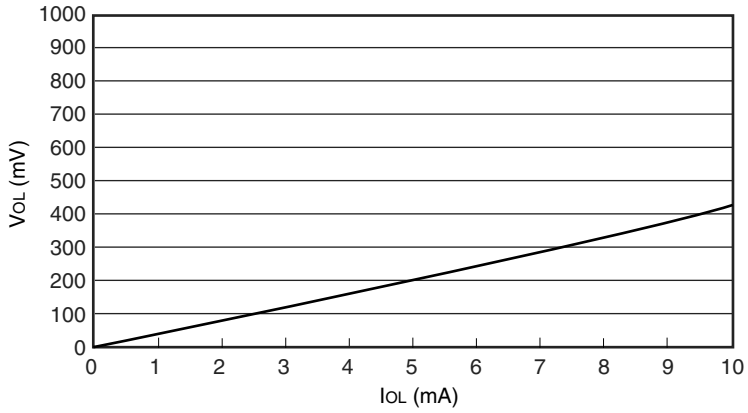
(V_{CC} - V_{OH}) – I_{OH}

T_A = +25 °C, V_{CC} = 4.5 V



V_{OL} – I_{OL}

T_A = +25 °C, V_{CC} = 4.5 V



H level input voltage/ L level input voltage
V_{IN} – V_{CC}

T_A = +25 °C